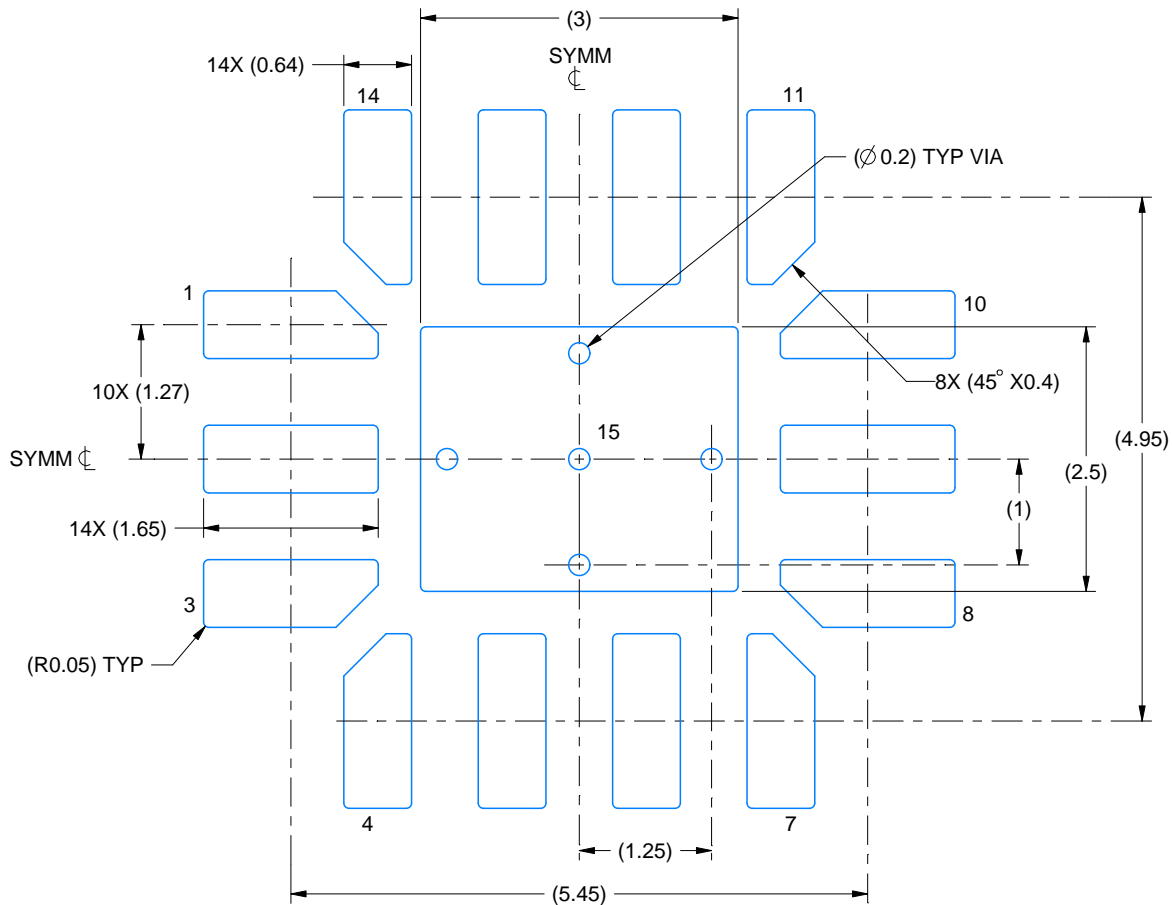


EXAMPLE BOARD LAYOUT

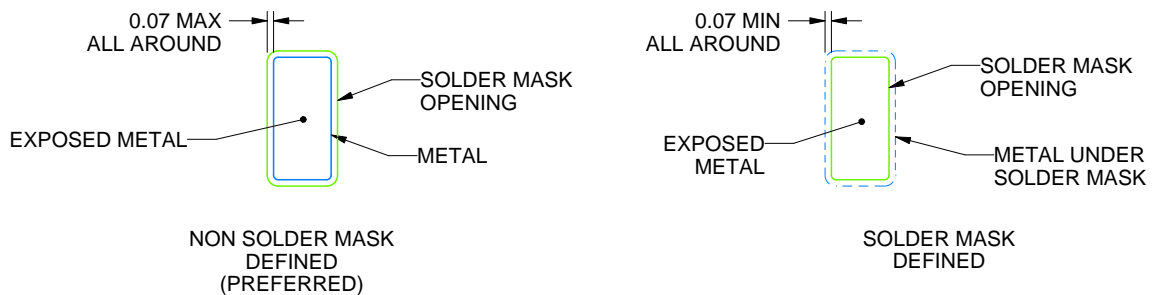
FFK0014A

LCCC - 1.87 mm max height

LEADLESS CERAMIC CHIP CARRIER



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 14X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

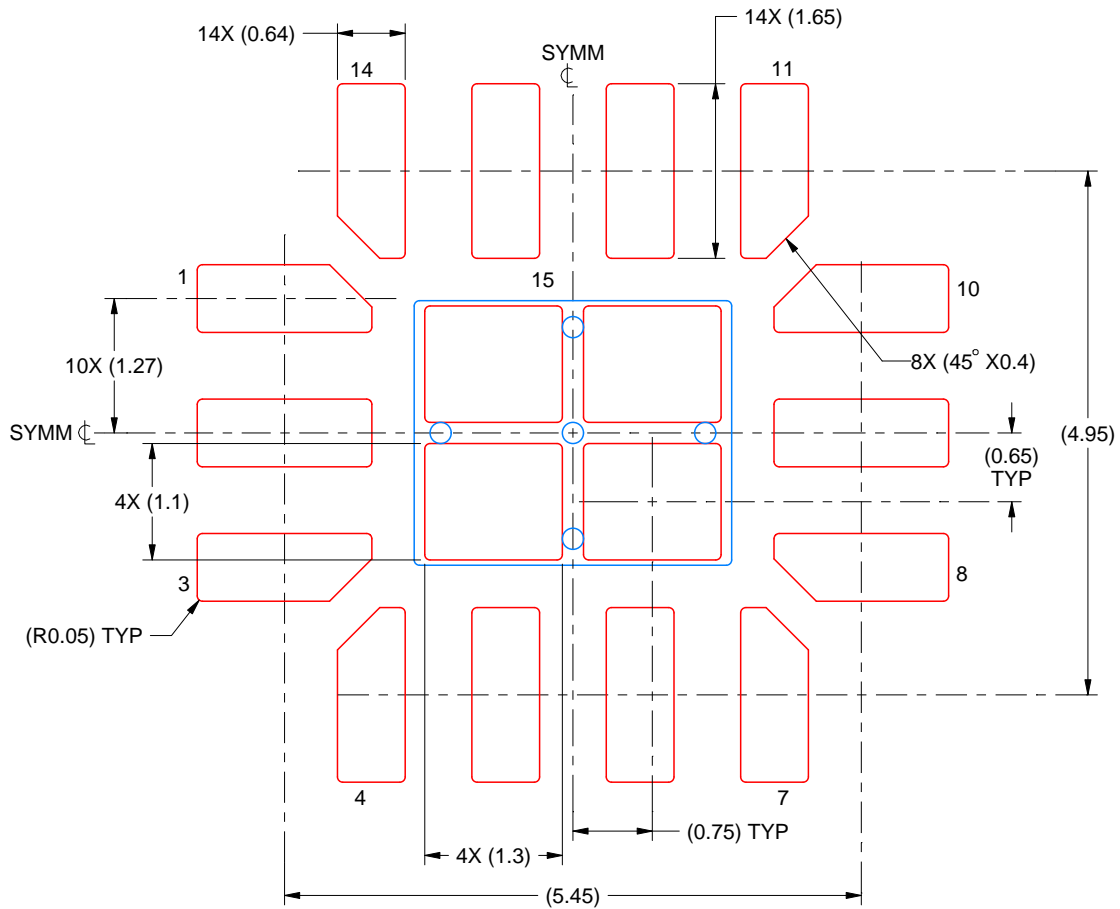
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

FFK0014A

LCCC - 1.87 mm max height

LEADLESS CERAMIC CHIP CARRIER



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 15:
76% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE: 14X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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